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Semiconductor apparatus including a plurality of clock paths and a semiconductor system using the same

Abstract

A semiconductor apparatus includes a plurality of clock paths, a first selecting circuit, and a multi-phase clock generating circuit. Each of the clock paths generates a corresponding clock signal pair according to an operation mode. The first selecting circuit outputs, as a reference clock signal pair, the corresponding clock signal pair. The multi-phase clock generating circuit generates first internal clock signals based on the reference clock signal pair.

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Background/Summary

CROSS-REFERENCES TO RELATED APPLICATION

(1) The present application claims priority under 35 U.S.C. § 119(a) to Korean application number 10-2022-0179292, filed on Dec. 20, 2022, in the Korean Intellectual Property Office, which is incorporated herein by reference in its entirety as set forth in full.

BACKGROUND

1. Technical Field

(2) Various embodiments generally relate to an integrated circuit technology, and, more particularly, to a semiconductor apparatus including a plurality of clock paths and a semiconductor system using the same.

2. Related Art

(3) An electronic device includes many electronic elements and a computer system as the electronic device includes many semiconductor apparatuses each configured by a semiconductor. The semiconductor apparatuses configuring the computer system may be synchronized with a system clock signal to perform data communication with each other. Each of the semiconductor apparatuses may generate an internal clock signal from the system clock signal to provide and receive data. The internal clock signal may have a frequency and/or a phase suitable for the performance of the semiconductor apparatus.

(4) The semiconductor apparatus may operate according to the system clock signal having various frequencies under various operational environments. To generate, from the system clock signal having various frequencies, an internal clock signal having a frequency suitable for the performance of the semiconductor apparatus, the semiconductor apparatus may be required to change a scheme of generating the internal clock signal according to the frequency of the system clock signal.

SUMMARY

(5) In an embodiment, a semiconductor apparatus may include a first clock path, a second clock path, a third clock path, a first selecting circuit, and a multi-phase clock generating circuit. The first clock path may be configured to buffer a system clock signal pair to generate a first clock signal pair in a first operation mode. The second clock path may be configured to multiply a frequency of the system clock signal pair to generate a second clock signal pair in a second operation mode. The third clock path may be configured to convert the system clock signal pair to a Complementary Metal-Oxide-Semiconductor (CMOS) level to generate a third clock signal pair in a third operation mode. The first selecting circuit may be configured to output, as a first reference clock signal pair, one of the first clock signal pair, the second clock signal pair, and the third clock signal pair according to the operation mode. The multi-phase clock generating circuit may be configured to generate first internal clock signals from the first reference clock signal pair.

(6) In an embodiment, a semiconductor apparatus may include a first clock path, a second clock path, a third clock path, a first selecting circuit, a multi-phase clock generating circuit, and a second selecting circuit. The first clock path may be configured to buffer a system clock signal pair to generate a first clock signal pair in a first operation mode. The second clock path may be configured to multiply a frequency of the system clock signal pair to generate a second clock signal pair in a second operation mode. The third clock path may be configured to convert the system clock signal pair to a Complementary Metal-Oxide-Semiconductor (CMOS) level to generate a third clock signal pair and configured to buffer the system clock signal pair to a Current Mode Logic (CML) level to generate a fourth clock signal pair, in a third operation mode. The first selecting circuit may be configured to select, as a first reference clock signal pair, one of the first clock signal pair, the second clock signal pair, and the third clock signal pair according to the operation mode. The multi-phase clock generating circuit may be configured to generate first internal clock signals, second internal clock signals, and a second reference clock signal pair from the first reference clock signal pair. The second selecting circuit may be configured to select, according to the operation mode, at least one of the second reference clock signal pair and the fourth clock signal pair to output the selected pair as a third internal clock signal pair.

(7) In an embodiment, a semiconductor apparatus may include a first clock path, a second clock path, a third clock path, a first selecting circuit, a multi-phase clock generating circuit, and a second selecting circuit. The first clock path may be configured to buffer a system clock signal pair to generate a first clock signal pair in a first operation mode. The second clock path may be configured to multiply a frequency of the system clock signal pair to generate a second clock signal pair in a second operation mode. The third clock path may be configured to convert the system clock signal pair to a Complementary Metal-Oxide-Semiconductor (CMOS) level to generate a third clock signal pair and configured to buffer the system clock signal pair to a Current Mode Logic (CML) level to generate a fourth clock signal pair, in a third operation mode. The first selecting circuit may be configured to selecting, as a first reference clock signal pair, one of the first clock signal pair, the second clock signal pair, and the third clock signal pair according to the operation mode. The multi-phase clock generating circuit may be configured to generate first internal clock signals, second internal clock signals, and a second reference clock signal pair based on at least one of a third internal clock signal pair and the first reference clock signal pair. The second selecting circuit may be configured to select one of the second reference clock signal pair and the fourth clock signal pair to output the selected pair as the third internal clock signal pair.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

- (1) FIG. 1 is a block diagram illustrating a configuration of a semiconductor system in accordance with an embodiment.
- (2) FIG. 2 is a block diagram illustrating a configuration of a semiconductor apparatus in accordance with an embodiment.
- (3) FIG. 3A is a timing diagram illustrating an operation of a semiconductor apparatus in a first operation mode in accordance with an embodiment.
- (4) FIG. 3B is a timing diagram illustrating an operation of a semiconductor apparatus in a second operation mode in accordance with an embodiment.
- (5) FIG. 3C is a timing diagram illustrating an operation of a semiconductor apparatus in a third operation mode in accordance with an embodiment.
- (6) FIG. 4 is a block diagram illustrating a configuration of a semiconductor apparatus in accordance with an embodiment.
- (7) FIG. 5 is a block diagram illustrating a configuration of a semiconductor apparatus in accordance with an embodiment.
- (8) FIG. 6 is a block diagram illustrating a configuration of a multi-phase clock generating circuit in accordance with an embodiment.

DETAILED DESCRIPTION

- (9) FIG. 1 is a block diagram illustrating a configuration of a semiconductor system **100** in accordance with an embodiment. Referring to FIG. 1, the semiconductor system **100** may include an external apparatus **110** and a semiconductor apparatus **120**. The semiconductor apparatus **120** may be synchronized with a system clock signal pair WCK/WCKB to perform data communication with an external apparatus **110**. The external apparatus **110** may provide various control signals required for the semiconductor apparatus **120** to operate for the data communication. The external apparatus **110** may include devices of various kinds. For example, the external apparatus **110** may be a host device such as a central processing unit (CPU), a graphic processing unit (GPU), a multi-media processor (MMP), a digital signal processor, an application processor (AP), a memory controller, and so forth. In an embodiment, the external apparatus **110** may include a test device or test equipment for testing the semiconductor apparatus **120**. For example, the semiconductor apparatus **120** may be a memory device. The memory device may include volatile memory or non-volatile memory. The volatile memory may include static random-access memory (static RAM: SRAM), dynamic RAM (DRAM), and synchronous DRAM (SDRAM). The non-volatile memory may include read only memory (ROM), programmable ROM (PROM), electrically erasable and programmable ROM (EEPROM), erasable programmable ROM (EPROM), flash memory, phase change RAM (PRAM), magnetic RAM (MRAM), resistive RAM (RRAM), ferroelectric RAM (FRAM), and so forth.
- (10) The semiconductor apparatus **120** may be coupled to the external apparatus **110** through a plurality of buses. Each of the plurality of buses may be a signal transmission path, a link, or a channel for transferring a signal. Each of the plurality of buses may include a plurality of transmission lines. The plurality of buses may include a clock bus **130**. The clock bus **130** may be unilateral from the external apparatus **110** to the semiconductor apparatus **120**. The semiconductor apparatus **120** may be coupled to the external apparatus **110** through the clock bus **130** and may receive the system clock signal pair WCK/WCKB from the external apparatus **110** through the clock bus **130**. In an embodiment, the clock bus **130** may include at least two (2) clock transmission lines, through which the system clock signal pair WCK/WCKB are transferred.
- (11) The semiconductor apparatus **120** may select, based on a frequency range of the system clock signal pair WCK/WCKB, an operation mode optimal for the operation of the semiconductor

apparatus **120**. When the system clock signal pair WCK/WCKB has a frequency within a first frequency range, the semiconductor apparatus **120** may operate in a first operation mode. When the system clock signal pair WCK/WCKB has a frequency within a second frequency range higher than the first frequency range, the semiconductor apparatus **120** may operate in a second operation mode. When the system clock signal pair WCK/WCKB has a frequency within a third frequency range higher than the second frequency range, the semiconductor apparatus **120** may operate in a third operation mode. The first to third frequency ranges may be classified respectively as a low frequency range, a middle frequency range, and a high frequency range. The classification of the frequency ranges might not be based on a particular value of the frequency. For example, when the system clock signal pair WCK/WCKB has a frequency within the low frequency range, the semiconductor apparatus **120** may operate in the first operation mode. When the system clock signal pair WCK/WCKB has a frequency within the middle frequency range, the semiconductor apparatus **120** may operate in the second operation mode. When the system clock signal pair WCK/WCKB has a frequency within the high frequency range, the semiconductor apparatus **120** may operate in the third operation mode.

(12) The semiconductor apparatus **120** may perform various operations according to the operation mode. For example, the semiconductor apparatus **120** may perform, in the first operation mode, a test operation together with the external apparatus **110**. The test operation performed in the first operation mode may include a wafer test operation. The wafer test operation may be performed to test the performance of the semiconductor apparatus **120** when the semiconductor apparatus **120** is formed on a wafer. The semiconductor apparatus **120** may perform, in the second operation mode, a test operation together with the external apparatus **110**. The test operation performed in the second operation mode may include a package test operation. The package test operation may be performed to test the performance of the semiconductor apparatus **120** when the semiconductor apparatus **120** is packaged. The semiconductor apparatus **120** may perform, in the third operation mode, a normal operation together with the external apparatus **110**. The normal operation may be any operation other than the above-described test operations and may be performed between the external apparatus **110** and the semiconductor apparatus **120**.

(13) The external apparatus **110** may generate the system clock signal pair WCK/WCKB having a frequency within the first frequency range and having a phase difference of 180° and may provide the system clock signal pair WCK/WCKB to the semiconductor apparatus **120**. The external apparatus **110** may generate the system clock signal pair WCK/WCKB having a frequency within the second frequency range and having a phase difference of 90° and may provide the system clock signal pair WCK/WCKB to the semiconductor apparatus **120**. The external apparatus **110** may generate the system clock signal pair WCK/WCKB having a frequency within the third frequency range and having a phase difference of 180° and may provide the system clock signal pair WCK/WCKB to the semiconductor apparatus **120**.

(14) The plurality of buses coupled between the external apparatus **110** and the semiconductor apparatus **120** may further include a data bus **140**, a command bus **150**, and an address bus **160**. The data bus **140** may be bilateral between the external apparatus **110** and the semiconductor apparatus **120**. Each of the command bus **150** and the address bus **160** may be unilateral from the external apparatus **110** to the semiconductor apparatus **120**.

(15) The semiconductor apparatus **120** may be coupled to the external apparatus **110** through the data bus **140** and may provide data to the external apparatus **110** or receive data from the external apparatus **110**, through the data bus **140**. In synchronization with the system clock signal pair WCK/WCKB, the external apparatus **110** may provide the semiconductor apparatus **120** with the data. The data bus **140** may include a plurality of data transmission lines and may transfer the data through the plurality of data transmission lines.

(16) The semiconductor apparatus **120** may be coupled to the external apparatus **110** through the command bus **150** and may receive, through the command bus **150**, a command signal CMD from

the external apparatus **110**. The semiconductor apparatus **120** may be coupled to the external apparatus **110** through the address bus **160** and may receive, through the address bus **160**, an address signal ADDR from the external apparatus **110**.

(17) The semiconductor apparatus **120** may include a plurality of clock paths. According to the operation mode and/or the frequency of the system clock signal pair WCK/WCKB, the semiconductor apparatus **120** may select at least one of the plurality of clock paths. Through the selected clock path, the semiconductor apparatus **120** may generate an internal clock signal from the system clock signal pair WCK/WCKB.

(18) The plurality of clock paths may include a first clock path **121**, a second clock path **122**, and a third clock path **123**. According to the operation mode, the semiconductor apparatus **120** may select one of the first to third clock paths **121**, **122**, and **123**. For example, the semiconductor apparatus **120** may select the first clock path **121** in the first operation mode, may select the second clock path **122** in the second operation mode, and may select the third clock path **123** in the third operation mode.

(19) In the first operation mode, the first clock path **121** may receive the system clock signal pair WCK/WCKB. The first clock path **121** may buffer the system clock signal pair WCK/WCKB to generate a first clock signal pair CK1/CK1B. The system clock signal pair WCK/WCKB may have a phase difference of 180° , and the first clock signal pair CK1/CK1B may have a phase difference of 180° . The first clock signal pair CK1/CK1B may have substantially the same frequency as the system clock signal pair WCK/WCKB. Without any frequency change or any voltage level conversion, the first clock path **121** might only buffer the system clock signal pair WCK/WCKB to generate the first clock signal pair CK1/CK1B.

(20) In the second operation mode, the second clock path **122** may receive the system clock signal pair WCK/WCKB. The second clock path **122** may multiply the frequency of the system clock signal pair WCK/WCKB to generate a second clock signal pair CK2/CK2B. The second clock signal pair CK2/CK2B may have a higher frequency than the system clock signal pair WCK/WCKB. For example, the second clock signal pair CK2/CK2B may have the frequency twice higher than the system clock signal pair WCK/WCKB. The system clock signal pair WCK/WCKB may have a phase difference of 90° , and the second clock signal pair CK2/CK2B may have a phase difference of 180° .

(21) In the third operation mode, the third clock path **123** may receive the system clock signal pair WCK/WCKB. The third clock path **123** may convert the level of the system clock signal pair WCK/WCKB to generate a third clock signal pair CK3/CK3B. In the third operation mode, the system clock signal pair WCK/WCKB may be signals swinging to a Current Mode Logic (CML) level. The third clock signal pair CK3/CK3B may be signals converted from the CML level to a Complementary Metal-Oxide-Semiconductor (CMOS) level. The third clock path **123** may convert the CML level, to which the system clock signal pair WCK/WCKB swings, to the CMOS level to generate the third clock signal pair CK3/CK3B swinging to the CMOS level. The CML level may correspond to a smaller swing width than the CMOS level, which corresponds to a full swing width. The CMOS level may correspond to a greater swing width than the CML level. The system clock signal pair WCK/WCKB may have a phase difference of 180° , and the third clock signal pair CK3/CK3B may have a phase difference of 180° . For example, the third clock signal pair CK3/CK3B may have substantially the same frequency as the system clock signal pair WCK/WCKB.

(22) The semiconductor apparatus **120** may further include a multi-phase clock generating circuit **124**. The multi-phase clock generating circuit **124** may receive the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B. Based on at least one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B, the multi-phase clock generating circuit **124** may generate at least one internal clock signal. For example, in the first operation mode, the

multi-phase clock generating circuit **124** may generate at least one internal clock signal based on the first clock signal pair CK1/CK1B. In the second operation mode, the multi-phase clock generating circuit **124** may generate at least one internal clock signal based on the second clock signal pair CK2/CK2B. In the third operation mode, the multi-phase clock generating circuit **124** may generate at least one internal clock signal based on the third clock signal pair CK3/CK3B.

(23) For example, the internal clock signals may include first internal clock signals INCK1, second internal clock signals INCK2, and a third internal clock signal pair INCK3/INCK3B. The multi-phase clock generating circuit **124** may output, as the third internal clock signal pair INCK3/INCK3B, one of the first to third clock signal pairs CK1/CK1B, CK2/CK2B, and CK3/CK3B. The multi-phase clock generating circuit **124** may divide one of the first to third clock signal pairs CK1/CK1B, CK2/CK2B, and CK3/CK3B to generate the first internal clock signals INCK1 and the second internal clock signals INCK2. The first internal clock signals INCK1 may include a plurality of internal clock signals. The first internal clock signals INCK1 may include an internal clock signal ICK, an internal clock signal QCK, an internal clock signal ICKB, and an internal clock signal QCKB. Each of the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may have a frequency twice lower than the system clock signal pair WCK/WCKB. The second internal clock signals INCK2 may include a plurality of internal clock signals. The second internal clock signals INCK2 may include an internal clock signal OCK0, an internal clock signal OCK2, an internal clock signal OCK4, and an internal clock signal OCK6 signal. Each of the second internal clock signals OCK0, OCK2, OCK4, and OCK6 may have a frequency four (4) times lower than the system clock signal pair WCK/WCKB. Described later will be details on how to generate the first internal clock signals INCK1 and the second internal clock signals INCK2.

(24) The semiconductor apparatus **120** may further include an internal circuit **125**. The internal circuit **125** may receive at least one internal clock from the multi-phase clock generating circuit **124**. The internal circuit **125** may receive the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B. The internal circuit **125** may operate based on the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B. For example, the internal circuit **125** may synchronize a control signal, which is provided from the external apparatus **110**, with at least one of the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B or may latch the control signal in synchronization with at least one of the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B. The control signal provided from the external apparatus **110** may include at least one of the command signal CMD and the address signal ADDR. In an embodiment, based on at least one of the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the internal circuit **125** may receive data from the external apparatus **110** or may provide data to the external apparatus **110**. In an embodiment, based on at least one of the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the internal circuit **125** may generate another internal clock signal.

(25) FIG. 2 is a block diagram illustrating a configuration of a semiconductor apparatus **200** in accordance with an embodiment. The semiconductor apparatus **200** may be applied as the semiconductor apparatus **120** illustrated in FIG. 1. The semiconductor apparatus **200** may determine, based on the frequency range of the system clock signal pair WCK/WCKB, an operation mode optimal for the operation of the semiconductor apparatus **200**. When the system clock signal pair WCK/WCKB has a frequency within the first frequency range, the semiconductor apparatus **200** may operate in the first operation mode. When the system clock signal pair WCK/WCKB has a frequency within the second frequency range higher than the first frequency range, the semiconductor apparatus **200** may operate in the second operation mode. When the system clock signal pair WCK/WCKB has a frequency within the third frequency range higher than

the second frequency range, the semiconductor apparatus **200** may operate in the third operation mode. The first to third frequency ranges may be classified respectively as the low frequency range, the middle frequency range, and the high frequency range. The classification of the frequency ranges might not be based on a particular value of the frequency. For example, when the system clock signal pair WCK/WCKB has a frequency within the low frequency range, the semiconductor apparatus **200** may operate in the first operation mode. When the system clock signal pair WCK/WCKB has a frequency within the middle frequency range, the semiconductor apparatus **200** may operate in the second operation mode. When the system clock signal pair WCK/WCKB has a frequency within the high frequency range, the semiconductor apparatus **200** may operate in the third operation mode.

(26) The semiconductor apparatus **200** may include a plurality of clock paths. According to the operation mode, the semiconductor apparatus **200** may select one of the plurality of clock paths to operate through the selected clock path. The plurality of clock paths may include a first clock path **210**, a second clock path **220**, and a third clock path **230**.

(27) The first clock path **210** may be activated in the first operation mode. When the first clock path **210** is activated, the first clock path **210** may receive the system clock signal pair WCK/WCKB and may buffer the system clock signal pair WCK/WCKB to generate the first clock signal pair CK1/CK1B. The system clock signal pair WCK/WCKB may have a phase difference of 180° , and the first clock signal pair CK1/CK1B may have a phase difference of 180° . The first clock signal pair CK1/CK1B may have the same frequency as the system clock signal pair WCK/WCKB. Without any frequency change or any voltage level conversion, the first clock path **210** might only buffer the system clock signal pair WCK/WCKB to generate the first clock signal pair CK1/CK1B. The first clock path **210** may include a first receiving circuit **211** and a buffer **212**. The first receiving circuit **211** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The first receiving circuit **211** may output the differentially amplified signals. The buffer **212** may buffer the output signals from the first receiving circuit **211**. That is, the buffer **212** may differentially amplify the output signals to generate a first clock signal pair CK1/CK1B. The buffer **212** may be a differential amplifier configured to differentially amplify the output signals from the first receiving circuit **211**.

(28) In an embodiment, the first clock path **210** may be selectively activated according to a first activating signal EN1. For example, the first activating signal EN1 may be enabled in the first operation mode to activate the first clock path **210**. The first receiving circuit **211** and the buffer **212** may be activated when the first activating signal EN1 is enabled. When the first receiving circuit **211** is activated, the first receiving circuit **211** may receive the system clock signal pair WCK/WCKB and may differentially amplify the system clock signal pair WCK/WCKB to output the differentially amplified signals. When the buffer **212** is activated, the buffer **212** may buffer the output signals from the first receiving circuit **211** to generate the first clock signal pair CK1/CK1B. When the first activating signal EN1 is disabled, at least one of the first receiving circuit **211** and the buffer **212** may be deactivated. When at least one of the first receiving circuit **211** and the buffer **212** is deactivated, the first clock path **210** might not receive the system clock signal pair WCK/WCKB and might not generate the first clock signal pair CK1/CK1B.

(29) The second clock path **220** may be activated in the second operation mode. When the second clock path **220** is activated, the second clock path **220** may receive the system clock signal pair WCK/WCKB and may multiply the frequency of the system clock signal pair WCK/WCKB to generate a second clock signal pair CK2/CK2B. The system clock signal pair WCK/WCKB may have a phase difference of 90° and the second clock signal pair CK2/CK2B may have a phase difference of 180° . The second clock signal pair CK2/CK2B may have a higher frequency than the system clock signal pair WCK/WCKB. For example, the second clock signal pair CK2/CK2B may have a frequency twice higher than the system clock signal pair WCK/WCKB. The second clock path **220** may include a second receiving circuit **221** and a multiplier **222**. The second receiving

circuit **221** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The second receiving circuit **221** may output the differentially amplified signals. The multiplier **222** may multiply the frequency of the output signals from the second receiving circuit **221** to generate the second clock signal pair CK2/CK2B. For example, the multiplier **222** may multiply the frequency of the output signals from the second receiving circuit **221** to generate the second clock signal pair CK2/CK2B having the frequency twice higher than the system clock signal pair WCK/WCKB.

(30) In an embodiment, the second clock path **220** may be selectively activated according to a second activating signal EN2. For example, the second activating signal EN2 may be enabled in the second operation mode to activate the second clock path **220**. The second receiving circuit **221** and the multiplier **222** may be activated when the second activating signal EN2 is enabled. When the second receiving circuit **221** is activated, the second receiving circuit **221** may receive the system clock signal pair WCK/WCKB and may differentially amplify the system clock signal pair WCK/WCKB to output the differentially amplified signals. When the multiplier **222** is activated, the multiplier **222** may multiply the frequency of the output signals from the second receiving circuit **221** to generate the second clock signal pair CK2/CK2B. When the second activating signal EN2 is disabled, at least one of the second receiving circuit **221** and the multiplier **222** may be deactivated. When at least one of the second receiving circuit **221** and the multiplier **222** is deactivated, the second clock path **220** might not receive the system clock signal pair WCK/WCKB and might not generate the second clock signal pair CK2/CK2B.

(31) The third clock path **230** may be activated in the third operation mode. When the third clock path **230** is activated, the third clock path **230** may receive the system clock signal pair WCK/WCKB and may convert the level of the system clock signal pair WCK/WCKB to generate a third clock signal pair CK3/CK3B. In the third operation mode, the system clock signal pair WCK/WCKB may be signals swinging to the CML level. The third clock signal pair CK3/CK3B may be a signal converted from the CML level to the CMOS level. The third clock path **230** may convert the CML level, to which the system clock signal pair WCK/WCKB swings, to the CMOS level to generate the third clock signal pair CK3/CK3B swinging to the CMOS level. The CML level may correspond to a less swing width than the CMOS level, which corresponds to a full swing width. The CMOS level may correspond to a greater swing width than the CML level. The system clock signal pair WCK/WCKB may have a phase difference of 180°, and the third clock signal pair CK3/CK3B may have a phase difference of 180°. For example, the third clock signal pair CK3/CK3B may have substantially the same frequency as the system clock signal pair WCK/WCKB. The third clock path **230** may include a third receiving circuit **231** and a first converter **232**. The third receiving circuit **231** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The third receiving circuit **231** may output the differentially amplified signals. The first converter **232** may convert the level of the output signals from the third receiving circuit **231** to generate the third clock signal pair CK3/CK3B. For example, the first converter **232** may convert, from the CML level to the CMOS level, the level of the output signals from the third receiving circuit **231**. The CML level may correspond to a less swing width than the CMOS level, which corresponds to a full swing width. The CMOS level may correspond to a greater swing width than the CML level.

(32) In an embodiment, the third clock path **230** may be selectively activated according to a third activating signal EN3. For example, the third activating signal EN3 may be enabled in the third operation mode to activate the third clock path **230**. The third receiving circuit **231** and the first converter **232** may be activated when the third activating signal EN3 is enabled. When the third receiving circuit **231** is activated, the third receiving circuit **231** may receive the system clock signal pair WCK/WCKB and may differentially amplify the system clock signal pair WCK/WCKB to output the differentially amplified signals. When the first converter **232** is activated, the first converter **232** may convert the level of the output signals from the third receiving circuit **231** to

generate the third clock signal pair CK3/CK3B. When the third activating signal EN3 is disabled, at least one of the third receiving circuit **231** and the first converter **232** may be deactivated. When at least one of the third receiving circuit **231** and the first converter **232** is deactivated, the third clock path **230** might not receive the system clock signal pair WCK/WCKB and might not generate the third clock signal pair CK3/CK3B.

(33) The semiconductor apparatus **200** may further include a first selecting circuit **240** and a multi-phase clock generating circuit **250**. According to the operation mode, the first selecting circuit **240** may selectively output, as a first reference clock signal pair RCK/RCKB, one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B. The first selecting circuit **240** may receive a first path selecting signal PSEL1 and may select, based on the first path selecting signal PSEL1, one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B. The first path selecting signal PSEL1 may be a signal indicating one of the first to third operation modes. For example, the first path selecting signal PSEL1 may be any of a first selecting signal SEL1, a second selecting signal SEL2, and a third selecting signal SEL3.

(34) The first path selecting signals PSEL1 may be generated from a control signal from the external apparatus **110** of FIG. **1** or may be generated according to a result of detecting, by the semiconductor apparatus **200**, the frequency of the system clock signal pair WCK/WCKB. In an embodiment, the first path selecting signals PSEL1 may include a plurality of bits and the first path selecting signals PSEL1 may be any of the first to third selecting signals SEL1, SEL2, and SEL3 through the change of logic levels of the plural bits. For example, the first selecting signal SEL1 may be enabled in the first operation mode to select the first clock path **210**, the second selecting signal SEL2 may be enabled in the second operation mode to select the second clock path **220**, and the third selecting signal SEL3 may be enabled in the third operation mode to select the third clock path **230**.

(35) In an embodiment, when the first selecting signal SEL1 is enabled, the first selecting circuit **240** may output, as the first reference clock signal pair RCK/RCKB, the first clock signal pair CK1/CK1B from the first clock path **210**. In an embodiment, when the second selecting signal SEL2 is enabled, the first selecting circuit **240** may output, as the first reference clock signal pair RCK/RCKB, the second clock signal pair CK2/CK2B from the second clock path **220**. In an embodiment, when the third selecting signal SEL3 is enabled, the first selecting circuit **240** may output, as the first reference clock signal pair RCK/RCKB, the third clock signal pair CK3/CK3B from the third clock path **230**.

(36) Based on the first reference clock signal pair RCK/RCKB, the multi-phase clock generating circuit **250** may generate first internal clock signals INCK1, second internal clock signals INCK2 and a third internal clock signal pair INCK3/INCK3B. For example, the multi-phase clock generating circuit **250** may output the first reference clock signal pair RCK/RCKB as the third internal clock signal pair INCK3/INCK3B. Also, the multi-phase clock generating circuit **250** may generate the first internal clock signals INCK1 by dividing the first reference clock signal pair RCK/RCKB. The first internal clock signals INCK1 may include a plurality of internal clock signals. Further, the multi-phase clock generating circuit **250** may generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The first internal clock signals INCK1 may include an internal clock signal ICK, an internal clock signal QCK, an internal clock signal ICKB, and an internal clock signal QCKB. The second internal clock signals INCK2 may include an internal clock signal OCK0, an internal clock signal OCK2, an internal clock signal OCK4, and an internal clock signal OCK6. In an embodiment, the first selecting circuit **240** may be integrated into the multi-phase clock generating circuit **250** to be an element within the multi-phase clock generating circuit **250**.

(37) The semiconductor apparatus **200** may further include a data path **260** and a memory core **270**. The data path **260** may receive the first internal clock signals INCK1, the second internal clock

signals INCK2, and the third internal clock signal pair INCK3/INCK3B. Based on the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the data path 260 may transfer, to the memory core 270, the data DQ provided from the external apparatus 110 through the data bus 140 of FIG. 1. Based on the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the data path 260 may transfer, to the external apparatus 110 through the data bus 140, data DQ provided from the memory core 270. In an embodiment, the data path 260 may serialize, by utilizing the first internal clock signals INCK1, the second internal clock signals INCK2 and the third internal clock signal pair INCK3/INCK3B, the data stored in the memory core 270 and may provide the serialized data to the external apparatus 110.

(38) FIG. 3A is a timing diagram illustrating an operation of the semiconductor apparatus 200 in accordance with an embodiment in the first operation mode. Hereinafter, described with reference to FIGS. 1, 2 and 3A will be the operation of the semiconductor apparatus 200. The external apparatus 110 may provide, through the clock bus 130, the semiconductor apparatus 200 with the system clock signal pair WCK/WCKB having a frequency within the low frequency range. The system clock signal pair WCK/WCKB may have a phase difference of 180°. When the system clock signal pair WCK/WCKB has a frequency within the low frequency range, the semiconductor apparatus 200 may operate in the first operation mode. When the semiconductor apparatus 200 operates in the first operation mode, the first clock path 210 may be activated. When the first clock path 210 is activated, the first clock path 210 may buffer the system clock signal pair WCK/WCKB to output the first clock signal pair CK1/CK1B. The first clock signal pair CK1/CK1B may have substantially the same frequency as the system clock signal pair WCK/WCKB. The first clock signal pair CK1/CK1B may have a phase difference of 180°, which is substantially the same as the system clock signal pair WCK/WCKB.

(39) The first selecting circuit 240 may receive the first clock signal pair CK1/CK1B from the first clock path 210. In the first operation mode, the first selecting circuit 240 may output the first clock signal pair CK1/CK1B as the first reference clock signal pair RCK/RCKB. Based on the first selecting signal SEL1 in the first operation mode, the first selecting circuit 240 may select the first clock signal pair CK1/CK1B as the first reference clock signal pair RCK/RCKB. Therefore, the first reference clock signal pair RCK/RCKB may have substantially the same frequency as the first clock signal pair CK1/CK1B. The first reference clock signal pair RCK/RCKB may have a phase difference of 180°, which is substantially the same as the first clock signal pair CK1/CK1B.

(40) The multi-phase clock generating circuit 250 may receive the first reference clock signal pair RCK/RCKB from the first selecting circuit 240. Based on the first reference clock signal pair RCK/RCKB, the multi-phase clock generating circuit 250 may generate the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B. The multi-phase clock generating circuit 250 may output the first reference clock signal pair RCK/RCKB as the third internal clock signal pair INCK3/INCK3B. Therefore, the third internal clock signal pair INCK3/INCK3B may have substantially the same frequency as the first reference clock signal pair RCK/RCKB. The third internal clock signal pair INCK3/INCK3B may have a phase difference of 180°, which is substantially the same as the first reference clock signal pair RCK/RCKB. Also, the multi-phase clock generating circuit 250 may generate the first internal clock signals INCK1 by dividing the first reference clock signal pair RCK/RCKB. The first internal clock signals INCK1 may include the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB. Each of the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may have a frequency twice lower than the system clock signal pair WCK/WCKB. The plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may sequentially have a phase difference of 90° between each other. Further, the multi-phase clock generating circuit 250 may generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The second internal clock signals INCK2 may include the plurality of second internal clock signals OCK0,

OCK2, OCK4, and OCK6. Each of the plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6 may have a frequency four (4) times lower than the system clock signal pair WCK/WCKB. The plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6 may sequentially have a phase difference of 90° between each other.

(41) FIG. 3B is a timing diagram illustrating an operation of the semiconductor apparatus 200 in the second operation mode in accordance with an embodiment. Hereinafter, described with reference to FIGS. 1, 2, and 3B will be the operation of the semiconductor apparatus 200. The external apparatus 110 may provide, through the clock bus 130, the semiconductor apparatus 200 with the system clock signal pair WCK/WCKB having a frequency within the middle frequency range. The system clock signal pair WCK/WCKB may have a phase difference of 90°. When the system clock signal pair WCK/WCKB has a frequency within the middle frequency range, the semiconductor apparatus 200 may operate in the second operation mode. When the semiconductor apparatus 200 operates in the second operation mode, the second clock path 220 may be activated. When the second clock path 220 is activated, the second clock path 220 may multiply the frequency of the system clock signal pair WCK/WCKB to generate the second clock signal pair CK2/CK2B. The second clock signal pair CK2/CK2B may have a higher frequency than the system clock signal pair WCK/WCKB. The second clock signal pair CK2/CK2B may have a phase difference of 180°. For example, when the second clock path 220 is activated, the multiplier 222 may multiply the frequency of the system clock signal pair WCK/WCKB to generate the second clock signal pair CK2/CK2B having the frequency twice higher than the system clock signal pair WCK/WCKB.

(42) The first selecting circuit 240 may receive the second clock signal pair CK2/CK2B from the second clock path 220. In the second operation mode, the first selecting circuit 240 may output the second clock signal pair CK2/CK2B as the first reference clock signal pair RCK/RCKB. Based on the second selecting signal SEL2 in the second operation mode, the first selecting circuit 240 may select the second clock signal pair CK2/CK2B as the first reference clock signal pair RCK/RCKB. The first reference clock signal pair RCK/RCKB may have substantially the same frequency as the second clock signal pair CK2/CK2B. The first reference clock signal pair RCK/RCKB may have substantially the same phase difference as the second clock signal pair CK2/CK2B.

(43) The multi-phase clock generating circuit 250 may receive the first reference clock signal pair RCK/RCKB from the first selecting circuit 240. Based on the first reference clock signal pair RCK/RCKB, the multi-phase clock generating circuit 250 may generate the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B. The multi-phase clock generating circuit 250 may output the first reference clock signal pair RCK/RCKB as the third internal clock signal pair INCK3/INCK3B. Therefore, the third internal clock signal pair INCK3/INCK3B may have substantially the same frequency as the first reference clock signal pair RCK/RCKB. The third internal clock signal pair INCK3/INCK3B may have a phase difference of 180°, which is substantially the same as the first reference clock signal pair RCK/RCKB. Also, the multi-phase clock generating circuit 250 may generate the first internal clock signals INCK1 by dividing the first reference clock signal pair RCK/RCKB. The first internal clock signals INCK1 may include the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB. Each of the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may have a frequency twice lower than the system clock signal pair WCK/WCKB. The plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may sequentially have a phase difference of 90° between each other. Further, the multi-phase clock generating circuit 250 may generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The second internal clock signals INCK2 may include the plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6. Each of the plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6 may have a frequency four (4) times lower than the system clock signal pair WCK/WCKB. The plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6

may sequentially have a phase difference of 90° between each other.

(44) FIG. 3C is a timing diagram illustrating an operation of the semiconductor apparatus **200** in the third operation mode in accordance with an embodiment. Hereinafter, described with reference to FIGS. 1, 2, and 3C will be the operation of the semiconductor apparatus **200**. The external apparatus **110** may provide, through the clock bus **130**, the semiconductor apparatus **200** with the system clock signal pair WCK/WCKB having a frequency within the high frequency range. The system clock signal pair WCK/WCKB may have a phase difference of 180° . When the system clock signal pair WCK/WCKB has a frequency within the high frequency range, the semiconductor apparatus **200** may operate in the third operation mode. When the semiconductor apparatus **200** operates in the third operation mode, the third clock path **230** may be activated. When the third clock path **230** is activated, the third clock path **230** may convert the level of the system clock signal pair WCK/WCKB to generate the third clock signal pair CK3/CK3B. Specifically, the third clock path **230** may convert the level of the system clock signal pair WCK/WCKB from the CML level to the CMOS level to generate the third clock signal pair CK3/CK3B. Even when the amplitude of the third clock signal pair CK3/CK3B may change, the third clock signal pair CK3/CK3B may have a phase difference of 180° , which is substantially the same as the system clock signal pair WCK/WCKB.

(45) The first selecting circuit **240** may receive the third clock signal pair CK3/CK3B from the third clock path **230**. In the third operation mode, the first selecting circuit **240** may output the third clock signal pair CK3/CK3B as the first reference clock signal pair RCK/RCKB. Based on the third selecting signal SEL3 in the third operation mode, the first selecting circuit **240** may select the third clock signal pair CK3/CK3B as the first reference clock signal pair RCK/RCKB. The first reference clock signal pair RCK/RCKB may have substantially the same frequency as the third clock signal pair CK3/CK3B. The first reference clock signal pair RCK/RCKB may have a phase difference of 180° , which is substantially the same as the third clock signal pair CK3/CK3B.

(46) The multi-phase clock generating circuit **250** may receive the first reference clock signal pair RCK/RCKB from the first selecting circuit **240**. Based on the first reference clock signal pair RCK/RCKB, the multi-phase clock generating circuit **250** may generate the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B. The multi-phase clock generating circuit **250** may output the first reference clock signal pair RCK/RCKB as the third internal clock signal pair INCK3/INCK3B. Therefore, the third internal clock signal pair INCK3/INCK3B may have substantially the same frequency as the first reference clock signal pair RCK/RCKB. The third internal clock signal pair INCK3/INCK3B may have a phase difference of 180° , which is substantially the same as the first reference clock signal pair RCK/RCKB. Also, the multi-phase clock generating circuit **250** may generate the first internal clock signals INCK1 by dividing the first reference clock signal pair RCK/RCKB. The first internal clock signals INCK1 may include the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB. Each of the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may have a frequency twice lower than the system clock signal pair WCK/WCKB. The plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may sequentially have a phase difference of 90° between each other. Further, the multi-phase clock generating circuit **250** may generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The second internal clock signals INCK2 may include the plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6. Each of the plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6 may have a frequency four (4) times lower than the system clock signal pair WCK/WCKB. The plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6 may sequentially have a phase difference of 90° between each other.

(47) Referring to FIGS. 2, 3B, and 3C, the system clock signal pair WCK/WCKB provided in the second operation mode may have a lower frequency than the system clock signal pair WCK/WCKB provided in the third operation mode. In the second operation mode, the second

clock path **220** may generate the second clock signal pair CK2/CK2B by multiplying the system clock signal pair WCK/WCKB. Therefore, the second clock path **220** may generate the second clock signal pair CK2/CK2B having substantially the same frequency as the third clock signal pair CK3/CK3B generated by the third clock path **230**. The first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B that are generated on the basis of the second clock signal pair CK2/CK2B in the second operation mode may have substantially the same frequency as the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B that are generated on the basis of the third clock signal pair CK3/CK3B in the third operation mode. The semiconductor apparatus **200** may generate the internal clock signals having the high frequency even when the semiconductor apparatus **200** receives, from the external apparatus **110**, the system clock signal pair WCK/WCKB having the low frequency in the second operation mode. Therefore, the semiconductor apparatus **200** may operate, during the package test, at substantially the same speed as the normal operation.

(48) FIG. **4** is a block diagram illustrating a configuration of a semiconductor apparatus **300** in accordance with an embodiment. The semiconductor apparatus **300** may be applied as the semiconductor apparatus **120** illustrated in FIG. **1**. The semiconductor apparatus **300** may determine, based on the frequency range of the system clock signal pair WCK/WCKB, an operation mode optimal for the operation of the semiconductor apparatus **300**. When the system clock signal pair WCK/WCKB has a frequency within the first frequency range, the semiconductor apparatus **300** may operate in the first operation mode. When the system clock signal pair WCK/WCKB has a frequency within the second frequency range higher than the first frequency range, the semiconductor apparatus **300** may operate in the second operation mode. When the system clock signal pair WCK/WCKB has a frequency within the third frequency range higher than the second frequency range, the semiconductor apparatus **300** may operate in the third operation mode. The first to third frequency ranges may be classified respectively as the low frequency range, the middle frequency range, and the high frequency range. The classification of the frequency ranges might not be based on a particular value of the frequency. For example, when the system clock signal pair WCK/WCKB has a frequency within the low frequency range, the semiconductor apparatus **300** may operate in the first operation mode. When the system clock signal pair WCK/WCKB has a frequency within the middle frequency range, the semiconductor apparatus **300** may operate in the second operation mode. When the system clock signal pair WCK/WCKB has a frequency within the high frequency range, the semiconductor apparatus **300** may operate in the third operation mode.

(49) The semiconductor apparatus **300** may include a plurality of clock paths. According to the operation mode, the semiconductor apparatus **300** may select one of the plurality of clock paths to operate through the selected clock path. The plurality of clock paths may include a first clock path **310**, a second clock path **320**, and a third clock path **330**.

(50) The first clock path **310** may be activated in the first operation mode. When the first clock path **310** is activated, the first clock path **310** may receive the system clock signal pair WCK/WCKB and may buffer the system clock signal pair WCK/WCKB to generate the first clock signal pair CK1/CK1B. The system clock signal pair WCK/WCKB may have a phase difference of 180°, and the first clock signal pair CK1/CK1B may have a phase difference of 180°. The first clock signal pair CK1/CK1B may have the same frequency as the system clock signal pair WCK/WCKB. The first clock path **310** may include a first receiving circuit **311** and a buffer **312**. The first receiving circuit **311** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The first receiving circuit **311** may output the differentially amplified signals. The buffer **312** may buffer the output signals from the first receiving circuit **311**. That is, the buffer **312** may differentially amplify the output signals to generate a first clock signal pair CK1/CK1B. The buffer **312** may be a differential amplifier configured to differentially amplify

the output signals from the first receiving circuit **311**.

(51) In an embodiment, the first clock path **310** may be selectively activated according to a first activating signal **EN1**. For example, the first activating signal **EN1** may be enabled in the first operation mode to activate the first clock path **310**. The first receiving circuit **311** and the buffer **312** may be activated when the first activating signal **EN1** is enabled. When the first receiving circuit **311** is activated, the first receiving circuit **311** may receive the system clock signal pair **WCK/WCKB** and may differentially amplify the system clock signal pair **WCK/WCKB** to output the differentially amplified signals. When the buffer **312** is activated, the buffer **312** may differentially amplify the output signals from the first receiving circuit **311** to generate the first clock signal pair **CK1/CK1B**. When the first activating signal **EN1** is disabled, at least one of the first receiving circuit **311** and the buffer **312** may be deactivated. When at least one of the first receiving circuit **311** and the buffer **312** is deactivated, the first clock path **310** might not receive the system clock signal pair **WCK/WCKB** and might not generate the first clock signal pair **CK1/CK1B**.

(52) The second clock path **320** may be activated in the second operation mode. When the second clock path **320** is activated, the second clock path **320** may receive the system clock signal pair **WCK/WCKB** and may multiply the frequency of the system clock signal pair **WCK/WCKB** to generate a second clock signal pair **CK2/CK2B**. The system clock signal pair **WCK/WCKB** may have a phase difference of 90° and the second clock signal pair **CK2/CK2B** may have a phase difference of 180° . The second clock signal pair **CK2/CK2B** may have a higher frequency than the system clock signal pair **WCK/WCKB**. For example, the second clock signal pair **CK2/CK2B** may have a frequency twice higher than the system clock signal pair **WCK/WCKB**. The second clock path **320** may include a second receiving circuit **321** and a multiplier **322**. The second receiving circuit **321** may receive the system clock signal pair **WCK/WCKB** to differentially amplify the system clock signal pair **WCK/WCKB**. The second receiving circuit **321** may output the differentially amplified signals. The multiplier **322** may multiply the frequency of the output signals from the second receiving circuit **321** to generate the second clock signal pair **CK2/CK2B**. For example, the multiplier **322** may multiply the frequency of the output signals from the second receiving circuit **321** to generate the second clock signal pair **CK2/CK2B** having the frequency twice higher than the system clock signal pair **WCK/WCKB**.

(53) In an embodiment, the second clock path **320** may be selectively activated according to a second activating signal **EN2**. For example, the second activating signal **EN2** may be enabled in the second operation mode to activate the second clock path **320**. The second receiving circuit **321** and the multiplier **322** may be activated when the second activating signal **EN2** is enabled. When the second receiving circuit **321** is activated, the second receiving circuit **321** may receive the system clock signal pair **WCK/WCKB** and may differentially amplify the system clock signal pair **WCK/WCKB** to output the differentially amplified signals. When the multiplier **322** is activated, the multiplier **322** may multiply the frequency of the output signals from the second receiving circuit **321** to generate the second clock signal pair **CK2/CK2B**. When the second activating signal **EN2** is disabled, at least one of the second receiving circuit **321** and the multiplier **322** may be deactivated. When at least one of the second receiving circuit **321** and the multiplier **322** is deactivated, the second clock path **320** might not receive the system clock signal pair **WCK/WCKB** and might not generate the second clock signal pair **CK2/CK2B**.

(54) The third clock path **330** may be activated in the third operation mode. When the third clock path **330** is activated, the third clock path **330** may receive the system clock signal pair **WCK/WCKB** and may convert the level of the system clock signal pair **WCK/WCKB** to generate a third clock signal pair **CK3/CK3B**. The third clock path **330** may buffer the system clock signal pair **WCK/WCKB** to the CML level and then may generate a fourth clock signal pair **CK4/CK4B**. Each of the third clock signal pair **CK3/CK3B** and the fourth clock signal pair **CK4/CK4B** may be a signal converted from the CML level to the CMOS level. The system clock signal pair

WCK/WCKB may have a phase difference of 180° . The third clock signal pair CK3/CK3B may have a phase difference of 180° . The fourth clock signal pair CK4/CK4B may have a phase difference of 180° . In an embodiment, each of the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may have substantially the same frequency as the system clock signal pair WCK/WCKB.

(55) The third clock path **330** may include a third receiving circuit **331**, a first converter **332**, a CML buffer **333** and a second converter **334**. The third receiving circuit **331** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The third receiving circuit **331** may output the differentially amplified signals. The first converter **332** may convert the level of the output signals from the third receiving circuit **331** to generate the third clock signal pair CK3/CK3B. The CML buffer **333** may buffer the output signals from the third receiving circuit **331**, the output signals having the CML level. Then, the third receiving circuit **331** may output the buffered signals having the CML level. The second converter **334** may convert the level of the output signals from the CML buffer **333** to generate the fourth clock signal pair CK4/CK4B. For example, each of the first converter **332** and the second converter **334** may convert, from the CML level to the CMOS level, the level of the system clock signal pair WCK/WCKB.

(56) The levels of the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may be converted from the CML level to the CMOS level through the first converter **332** and the second converter **334**, respectively. Ideally, the system clock signal pair WCK/WCKB, the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may have substantially the same frequency and substantially the same phase. However, the third clock signal pair CK3/CK3B may be generated by directly converting the output signals from the third receiving circuit **331** the CMOS level. On the other hand, the fourth clock signal pair CK4/CK4B may be converted to the CMOS level by the second converter **334** after the output signals from the third receiving circuit **331** and having the CML level are additionally buffered by the CML buffer **333**. Therefore, the fourth clock signal pair CK4/CK4B may have better signal characteristics than the third clock signal pair CK3/CK3B although the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may have substantially the same frequency and substantially the same phase.

(57) In an embodiment, the third clock path **330** may be selectively activated according to a third activating signal EN3. For example, the third activating signal EN3 may be enabled in the third operation mode to activate the third clock path **330**. The third receiving circuit **331**, the first converter **332**, the CML buffer **333**, and the second converter **334** may be activated when the third activating signal EN3 is enabled. When the third receiving circuit **331** is activated, the third receiving circuit **331** may receive the system clock signal pair WCK/WCKB and may differentially amplify the system clock signal pair WCK/WCKB to output the differentially amplified signals. When the first converter **332** is activated, the first converter **332** may convert, from the CML level to the CMOS level, the level of the output signals from the third receiving circuit **331** to generate the third clock signal pair CK3/CK3B. When the CML buffer **333** is activated, the CML buffer **333** may buffer the output signals from the third receiving circuit **331** to output the buffered signals. When the second converter **334** is activated, the second converter **334** may convert, from the CML level to the CMOS level, the level of the output signals from the CML buffer **333** to generate the fourth clock signal pair CK4/CK4B. When the third activating signal EN3 is disabled, the third receiving circuit **331**, the first converter **332**, the CML buffer **333**, and the second converter **334** may selectively be deactivated. In an embodiment, when the third clock path **330** is deactivated, the third clock path **330** might not receive the system clock signal pair WCK/WCKB and might not generate the third clock signal pair CK3/CK3B or the fourth clock signal pair CK4/CK4B.

(58) The semiconductor apparatus **300** may further include a first selecting circuit **340**, a multi-phase clock generating circuit **350**, and a second selecting circuit **380**. According to the operation

mode, the first selecting circuit **340** may selectively output, as a first reference clock signal pair RCK/RCKB, one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B and the third clock signal pair CK3/CK3B. The first selecting circuit **340** may receive a first path selecting signal PSEL1. Based on the first path selecting signal PSEL1, the first selecting circuit **340** may output, as the first reference clock signal pair RCK/RCKB, one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B and the third clock signal pair CK3/CK3B. The first path selecting signal PSEL1 may be a signal indicating one of the first to third operation modes. For example, the first path selecting signal PSEL1 may be any of a first selecting signal SEL1, a second selecting signal SEL2 and a third selecting signal SEL3.

(59) The first path selecting signals PSEL1 may be generated from a control signal from the external apparatus **110** of FIG. **1** or may be generated according to a result of detecting, by the semiconductor apparatus **300**, the frequency of the system clock signal pair WCK/WCKB. In an embodiment, the first path selecting signals PSEL1 may include a plurality of bits and the first path selecting signals PSEL1 may be any of the first to third selecting signals SEL1, SEL2, and SEL3 through the change of logic levels of the plural bits. Based on the indication of one of the first to third selecting signals SEL1, SEL2, and SEL3 according to the change of logic levels of the plural bits within the first path selecting signals PSEL1, the indicated one of the first to third selecting signals SEL1, SEL2, and SEL3 may be enabled. For example, the first selecting signal SEL1 may be enabled in the first operation mode to select the first clock path **310**, the second selecting signal SEL2 may be enabled in the second operation mode to select the second clock path **320**, and the third selecting signal SEL3 may be enabled in the third operation mode to select the third clock path **330**.

(60) In an embodiment, when the first selecting signal SEL1 is enabled, the first selecting circuit **340** may output, as the first reference clock signal pair RCK/RCKB, the first clock signal pair CK1/CK1B from the first clock path **310**. In an embodiment, when the second selecting signal SEL2 is enabled, the first selecting circuit **340** may output, as the first reference clock signal pair RCK/RCKB, the second clock signal pair CK2/CK2B from the second clock path **320**. In an embodiment, when the third selecting signal SEL3 is enabled, the first selecting circuit **340** may output, as the first reference clock signal pair RCK/RCKB, the third clock signal pair CK3/CK3B from the third clock path **330**.

(61) Based on the first reference clock signal pair RCK/RCKB, the multi-phase clock generating circuit **350** may generate first internal clock signals INCK1, second internal clock signals INCK2, and a second reference clock signal pair RCK2/RCK2B.

(62) For example, the multi-phase clock generating circuit **350** may output the first reference clock signal pair RCK/RCKB as the second reference clock signal pair RCK2/RCK2B. The first reference clock signal pair RCK/RCKB may have a phase difference of 180°. The second reference clock signal pair RCK2/RCK2B may have substantially the same phase difference and substantially the same frequency as the first reference clock signal pair RCK/RCKB. Also, the multi-phase clock generating circuit **350** may generate the first internal clock signals INCK1 by dividing the first reference clock signal pair RCK/RCKB. The first internal clock signals INCK1 may include a plurality of internal clock signals. Further, the multi-phase clock generating circuit **350** may generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The second internal clock signals INCK2 may include a plurality of internal clock signals. The first internal clock signals INCK1 may include an internal clock signal ICK, an internal clock signal QCK, an internal clock signal ICKB, and an internal clock signal QCKB. The second internal clock signals INCK2 may include an internal clock signal OCK0, an internal clock signal OCK2, an internal clock signal OCK4, and an internal clock signal OCK6. In an embodiment, the first selecting circuit **340** may be integrated into the multi-phase clock generating circuit **350** to be an element within the multi-phase clock generating circuit **350**.

(63) The second selecting circuit **380** may select one of the second reference clock signal pair

RCK2/RCK2B and the fourth clock signal pair CK4/CK4B to output the selected pair as a third internal clock signal pair INCK3/INCK3B. The second selecting circuit 380 may receive the second reference clock signal pair RCK2/RCK2B from the multi-phase clock generating circuit 350, may receive the fourth clock signal pair CK4/CK4B from the third clock path 330 and may output, as the third internal clock signal pair INCK3/INCK3B, a selected one of the second reference clock signal pair RCK2/RCK2B and the fourth clock signal pair CK4/CK4B. The second selecting circuit 380 may receive a second path selecting signal PSEL2. Based on the second path selecting signal PSEL2, the second selecting circuit 380 may output, as the third internal clock signal pair INCK3/INCK3B, at least one of the second reference clock signal pair RCK2/RCK2B and the fourth clock signal pair CK4/CK4B. For example, when the second path selecting signal PSEL2 is enabled, the second selecting circuit 380 may output, as the third internal clock signal pair INCK3/INCK3B, the second reference clock signal pair RCK2/RCK2B from the multi-phase clock generating circuit 350. For example, when the second path selecting signal PSEL2 is disabled, the second selecting circuit 380 may output, as the third internal clock signal pair INCK3/INCK3B, the fourth clock signal pair CK4/CK4B from the third clock path 330. In an embodiment, when the second path selecting signal PSEL2 is disabled, the second selecting circuit 380 may output, as the third internal clock signal pair INCK3/INCK3B, the second reference clock signal pair RCK2/RCK2B from the multi-phase clock generating circuit 350. In an embodiment, when the second path selecting signal PSEL2 is enabled, the second selecting circuit 380 may output, as the third internal clock signal pair INCK3/INCK3B, the fourth clock signal pair CK4/CK4B from the third clock path 330. The second path selecting signal PSEL2 may be generated from a control signal from the external apparatus 110 of FIG. 1 or may be generated according to a result of detecting, by the semiconductor apparatus 300, the frequency of the system clock signal pair WCK/WCKB. In an embodiment, the second path selecting signal PSEL2 may include a plurality of bits and may be enabled or disabled according to the change of logic levels of the plural bits.

(64) The semiconductor apparatus 300 may further include a data path 360 and a memory core 370. The data path 360 may receive the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B. Based on the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the data path 360 may transfer, to the memory core 370, the data DQ provided from the external apparatus 110 through the data bus 140 of FIG. 1. Based on the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the data path 360 may transfer, to the external apparatus 110 through the data bus 140, data DQ provided from the memory core 370. In an embodiment, the data path 360 may serialize, by utilizing the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the data output from the memory core 370 and may provide the serialized data to the external apparatus 110.

(65) FIG. 5 is a block diagram illustrating a configuration of a semiconductor apparatus 400 in accordance with an embodiment. The semiconductor apparatus 400 may be applied as the semiconductor apparatus 120 illustrated in FIG. 1. The semiconductor apparatus 400 may determine, based on the frequency range of the system clock signal pair WCK/WCKB, an operation mode optimal for the operation of the semiconductor apparatus 400. When the system clock signal pair WCK/WCKB has a frequency within the first frequency range, the semiconductor apparatus 400 may operate in the first operation mode. When the system clock signal pair WCK/WCKB has a frequency within the second frequency range higher than the first frequency range, the semiconductor apparatus 400 may operate in the second operation mode. When the system clock signal pair WCK/WCKB has a frequency within the third frequency range higher than the second frequency range, the semiconductor apparatus 400 may operate in the third operation mode. The first to third frequency ranges may be classified respectively as the low frequency

range, the middle frequency range, and the high frequency range. The classification of the frequency ranges might not be based on a particular value of the frequency. For example, when the system clock signal pair WCK/WCKB has a frequency within the low frequency range, the semiconductor apparatus **400** may operate in the first operation mode. When the system clock signal pair WCK/WCKB has a frequency within the middle frequency range, the semiconductor apparatus **400** may operate in the second operation mode. When the system clock signal pair WCK/WCKB has a frequency within the high frequency range, the semiconductor apparatus **400** may operate in the third operation mode.

(66) The semiconductor apparatus **400** may include a plurality of clock paths. According to the operation mode, the semiconductor apparatus **400** may select one of the plurality of clock paths to operate through the selected clock path. The plurality of clock paths may include a first clock path **410**, a second clock path **420**, and a third clock path **430**.

(67) The first clock path **410** may be activated in the first operation mode. When the first clock path **410** is activated, the first clock path **410** may receive the system clock signal pair WCK/WCKB and may buffer the system clock signal pair WCK/WCKB to generate the first clock signal pair CK1/CK1B. The system clock signal pair WCK/WCKB may have a phase difference of 180° , and the first clock signal pair CK1/CK1B may have a phase difference of 180° . The first clock signal pair CK1/CK1B may have the same frequency as the system clock signal pair WCK/WCKB. The first clock path **410** may include a first receiving circuit **411** and a buffer **412**. The first receiving circuit **411** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The first receiving circuit **411** may output the differentially amplified signals. The buffer **412** may buffer the output signals from the first receiving circuit **411**. That is, the buffer **412** may differentially amplify the output signals to generate a first clock signal pair CK1/CK1B. The buffer **412** may be a differential amplifier configured to differentially amplify the output signals from the first receiving circuit **411**.

(68) In an embodiment, the first clock path **410** may be selectively activated according to a first activating signal EN1. For example, the first activating signal EN1 may be enabled in the first operation mode to activate the first clock path **410**. The first receiving circuit **411** and the buffer **412** may be activated when the first activating signal EN1 is enabled. When the first receiving circuit **411** is activated, the first receiving circuit **411** may receive the system clock signal pair WCK/WCKB and may differentially amplify the system clock signal pair WCK/WCKB to output the differentially amplified signals. When the buffer **412** is activated, the buffer **412** may differentially amplify the output signals from the first receiving circuit **411** to generate the first clock signal pair CK1/CK1B. When the first activating signal EN1 is disabled, at least one of the first receiving circuit **411** and the buffer **412** may be deactivated. When at least one of the first receiving circuit **411** and the buffer **412** is deactivated, the first clock path **410** might not receive the system clock signal pair WCK/WCKB and might not generate the first clock signal pair CK1/CK1B.

(69) The second clock path **420** may be activated in the second operation mode. When the second clock path **420** is activated, the second clock path **420** may receive the system clock signal pair WCK/WCKB and may multiply the frequency of the system clock signal pair WCK/WCKB to generate a second clock signal pair CK2/CK2B. The system clock signal pair WCK/WCKB may have a phase difference of 90° and the second clock signal pair CK2/CK2B may have a phase difference of 180° . The second clock signal pair CK2/CK2B may have a higher frequency than the system clock signal pair WCK/WCKB. For example, the second clock signal pair CK2/CK2B may have a frequency twice higher than the system clock signal pair WCK/WCKB. The second clock path **420** may include a second receiving circuit **421** and a multiplier **422**. The second receiving circuit **421** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The second receiving circuit **421** may output the differentially amplified signals. The multiplier **422** may multiply the frequency of the output

signals from the second receiving circuit **421** to generate the second clock signal pair CK2/CK2B. For example, the multiplier **422** may multiply the frequency of the output signals from the second receiving circuit **421** to generate the second clock signal pair CK2/CK2B having the frequency twice higher than the system clock signal pair WCK/WCKB.

(70) In an embodiment, the second clock path **420** may be selectively activated according to a second activating signal EN2. For example, the second activating signal EN2 may be enabled in the second operation mode to activate the second clock path **420**. The second receiving circuit **421** and the multiplier **422** may be activated when the second activating signal EN2 is enabled. When the second receiving circuit **421** is activated, the second receiving circuit **421** may receive the system clock signal pair WCK/WCKB and may differentially amplify the system clock signal pair WCK/WCKB to output the differentially amplified signals. When the multiplier **422** is activated, the multiplier **422** may multiply the frequency of the output signals from the second receiving circuit **421** to generate the second clock signal pair CK2/CK2B. When the second activating signal EN2 is disabled, at least one of the second receiving circuit **421** and the multiplier **422** may be deactivated. When at least one of the second receiving circuit **421** and the multiplier **422** is deactivated, the second clock path **420** might not receive the system clock signal pair WCK/WCKB and might not generate the second clock signal pair CK2/CK2B.

(71) The third clock path **430** may be activated in the third operation mode. When the third clock path **430** is activated, the third clock path **430** may receive the system clock signal pair WCK/WCKB and may convert the level of the system clock signal pair WCK/WCKB to generate a third clock signal pair CK3/CK3B. The third clock path **430** may buffer the system clock signal pair WCK/WCKB having the CML level and then may convert the level of the system clock signal pair WCK/WCKB to generate a fourth clock signal pair CK4/CK4B. Each of the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may be a signal converted from the CML level to the CMOS level. The system clock signal pair WCK/WCKB may have a phase difference of 180°. The third clock signal pair CK3/CK3B may have a phase difference of 180°. The fourth clock signal pair CK4/CK4B may have a phase difference of 180°. In an embodiment, each of the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may have substantially the same frequency as the system clock signal pair WCK/WCKB.

(72) The third clock path **430** may include a third receiving circuit **431**, a first converter **432**, a CML buffer **433**, and a second converter **434**. The third receiving circuit **431** may receive the system clock signal pair WCK/WCKB to differentially amplify the system clock signal pair WCK/WCKB. The third receiving circuit **431** may output the differentially amplified signals. The first converter **432** may convert the level of the output signals from the third receiving circuit **431** to generate the third clock signal pair CK3/CK3B. The CML buffer **433** may buffer the output signals from the third receiving circuit **431**, the output signals having the CML level. Then, the third receiving circuit **431** may output the buffered signals having the CML level. The second converter **434** may convert the level of the output signals from the CML buffer **433** to generate the fourth clock signal pair CK4/CK4B. For example, each of the first converter **432** and the second converter **434** may convert, from the CML level to the CMOS level, the level of the system clock signal pair WCK/WCKB. The CML level may correspond to a less swing width than the CMOS level, which corresponds to a full swing width. The CMOS level may correspond to a greater swing width than the CML level.

(73) The levels of the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may be converted from the CML level to the CMOS level through the first converter **432** and the second converter **434**, respectively. Ideally, the system clock signal pair WCK/WCKB, the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may have substantially the same frequency and substantially the same phase. However, the third clock signal pair CK3/CK3B may be generated by directly converting the output signals from the third receiving circuit **431** to the CMOS level. On the other hand, the fourth clock signal pair

CK4/CK4B may be converted to the CML level by the second converter **434** after the output signals from the third receiving circuit **431** are buffered to the CML level by the CML buffer **433**. Therefore, the fourth clock signal pair CK4/CK4B may have better signal characteristics than the third clock signal pair CK3/CK3B although the third clock signal pair CK3/CK3B and the fourth clock signal pair CK4/CK4B may have substantially the same frequency and substantially the same phase.

(74) In an embodiment, the third clock path **430** may be selectively activated according to a third activating signal EN3. For example, the third activating signal EN3 may be enabled in the third operation mode to activate the third clock path **430**. The third receiving circuit **431**, the first converter **432**, the CML buffer **433**, and the second converter **434** may be activated when the third activating signal EN3 is enabled. When the third receiving circuit **431** is activated, the third receiving circuit **431** may receive the system clock signal pair WCK/WCKB and may differentially amplify the system clock signal pair WCK/WCKB to output the differentially amplified signals. When the first converter **432** is activated, the first converter **432** may convert, from the CML level to the CMOS level, the level of the output signals from the third receiving circuit **431** to generate the third clock signal pair CK3/CK3B. When the CML buffer **433** is activated, the CML buffer **433** may buffer the output signals from the third receiving circuit **431** to output the buffered signals. When the second converter **434** is activated, the second converter **434** may convert, from the CML level to the CMOS level, the level of the output signals from the CML buffer **433** to generate the fourth clock signal pair CK4/CK4B. When the third activating signal EN3 is disabled, the third receiving circuit **431**, the first converter **432**, the CML buffer **433**, and the second converter **434** may selectively be deactivated. In an embodiment, when the third clock path **430** is deactivated, the third clock path **430** might not receive the system clock signal pair WCK/WCKB and might not generate the third clock signal pair CK3/CK3B or the fourth clock signal pair CK4/CK4B.

(75) The semiconductor apparatus **400** may further include a first selecting circuit **440**, a multi-phase clock generating circuit **450**, and a second selecting circuit **480**. According to the operation mode, the first selecting circuit **440** may selectively output, as a first reference clock signal pair RCK/RCKB, one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B. The first selecting circuit **440** may receive a first path selecting signal PSEL1. Based on the first path selecting signal PSEL1, the first selecting circuit **440** may select one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B. The first path selecting signal PSEL1 may be a signal indicating one of the first to third operation modes. For example, the first path selecting signal PSEL1 may be any of a first selecting signal SEL1, a second selecting signal SEL2, and a third selecting signal SEL3.

(76) The first path selecting signals PSEL1 may be generated from a control signal from the external apparatus **110** of FIG. 1 or may be generated according to a result of detecting, by the semiconductor apparatus **400**, the frequency of the system clock signal pair WCK/WCKB. In an embodiment, the first path selecting signals PSEL1 may include a plurality of bits, and the first path selecting signals PSEL1 may be any of the first to third selecting signals SEL1, SEL2, and SEL3 through the change of logic levels of the plural bits. Based on the indication of one of the first to third selecting signals SEL1, SEL2, and SEL3 according to the change of logic levels of the plural bits within the first path selecting signals PSEL1, the indicated one of the first to third selecting signals SEL1, SEL2, and SEL3 may be enabled. For example, the first selecting signal SEL1 may be enabled in the first operation mode to select the first clock path **410**, the second selecting signal SEL2 may be enabled in the second operation mode to select the second clock path **420**, and the third selecting signal SEL3 may be enabled in the third operation mode to select the third clock path **430**.

(77) In an embodiment, when the first selecting signal SEL1 is enabled, the first selecting circuit **440** may output, as the first reference clock signal pair RCK/RCKB, the first clock signal pair

CK1/CK1B from the first clock path **410**. In an embodiment, when the second selecting signal SEL2 is enabled, the first selecting circuit **440** may output, as the first reference clock signal pair RCK/RCKB, the second clock signal pair CK2/CK2B from the second clock path **420**. In an embodiment, when the third selecting signal SEL3 is enabled, the first selecting circuit **440** may output, as the first reference clock signal pair RCK/RCKB, the third clock signal pair CK3/CK3B from the third clock path **430**.

(78) The multi-phase clock generating circuit **450** may receive the first reference clock signal pair RCK/RCKB from the first selecting circuit **440** and may receive the third internal clock signal pair INCK3/INCK3B from the second selecting circuit **480**. The multi-phase clock generating circuit **450** may output, as a second reference clock signal pair RCK2/RCK2B, at least one of the first reference clock signal pair RCK/RCKB and the third internal clock signal pair INCK3/INCK3B. The first reference clock signal pair RCK/RCKB and the second reference clock signal pair RCK2/RCK2B may have substantially the same phase difference and substantially the same frequency. The third internal clock signal pair INCK3/INCK3B and the second reference clock signal pair RCK2/RCK2B may have substantially the same phase difference and substantially the same frequency.

(79) Also, the multi-phase clock generating circuit **450** may generate the first internal clock signals INCK1 by dividing at least one of the first reference clock signal pair RCK/RCKB and the third internal clock signal pair INCK3/INCK3B. The first internal clock signals INCK1 may include a plurality of internal clock signals. Further, the multi-phase clock generating circuit **450** may generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The second internal clock signals INCK2 may include a plurality of internal clock signals. The first internal clock signals INCK1 may include an internal clock signal ICK, an internal clock signal QCK, an internal clock signal ICKB, and an internal clock signal QCKB. The second internal clock signals INCK2 may include an internal clock signal OCK0, an internal clock signal OCK2, an internal clock signal OCK4, and an internal clock signal OCK6. In an embodiment, the first selecting circuit **440** may be integrated into the multi-phase clock generating circuit **450** to be an element within the multi-phase clock generating circuit **450**.

(80) The second selecting circuit **480** may output, as the third internal clock signal pair INCK3/INCK3B, one of the second reference clock signal pair RCK2/RCK2B and the fourth clock signal pair CK4/CK4B. The second selecting circuit **480** may receive the second reference clock signal pair RCK2/RCK2B from the multi-phase clock generating circuit **450**, may receive the fourth clock signal pair CK4/CK4B from the third clock path **430** and may output, as the third internal clock signal pair INCK3/INCK3B, a selected one of the second reference clock signal pair RCK2/RCK2B and the fourth clock signal pair CK4/CK4B. The second selecting circuit **480** may receive a second path selecting signal PSEL2. Based on the second path selecting signal PSEL2, the second selecting circuit **480** may output, as the third internal clock signal pair INCK3/INCK3B, at least one of the second reference clock signal pair RCK2/RCK2B and the fourth clock signal pair CK4/CK4B. For example, when the second path selecting signal PSEL2 is enabled, the second selecting circuit **480** may output, as the third internal clock signal pair INCK3/INCK3B, the second reference clock signal pair RCK2/RCK2B from the multi-phase clock generating circuit **450**. For example, when the second path selecting signal PSEL2 is disabled, the second selecting circuit **480** may output, as the third internal clock signal pair INCK3/INCK3B, the fourth clock signal pair CK4/CK4B from the third clock path **430**. In an embodiment, when the second path selecting signal PSEL2 is disabled, the second selecting circuit **480** may output, as the third internal clock signal pair INCK3/INCK3B, the second reference clock signal pair RCK2/RCK2B from the multi-phase clock generating circuit **450**. In an embodiment, when the second path selecting signal PSEL2 is enabled, the second selecting circuit **480** may output, as the third internal clock signal pair INCK3/INCK3B, the fourth clock signal pair CK4/CK4B from the third clock path **430**. The second path selecting signal PSEL2 may be generated from a control signal from the external

apparatus **110** of FIG. **1** or may be generated according to a result of detecting, by the semiconductor apparatus **400**, the frequency of the system clock signal pair WCK/WCKB. In an embodiment, the second path selecting signal PSEL2 may include a plurality of bits and may be enabled or disabled according to the change of logic levels of the plural bits.

(81) The multi-phase clock generating circuit **450** may receive the first reference clock signal pair RCK/RCKB from the first selecting circuit **440** and may receive the third internal clock signal pair INCK3/INCK3B from the second selecting circuit **480**. The multi-phase clock generating circuit **450** may output, as a second reference clock signal pair RCK2/RCK2B, at least one of the first reference clock signal pair RCK/RCKB and the third internal clock signal pair INCK3/INCK3B. The first reference clock signal pair RCK/RCKB and the second reference clock signal pair RCK2/RCK2B may have substantially the same phase difference and substantially the same frequency. The third internal clock signal pair INCK3/INCK3B and the second reference clock signal pair RCK2/RCK2B may have substantially the same phase difference and substantially the same frequency.

(82) The semiconductor apparatus **400** may further include a data path **460** and a memory core **470**. The data path **460** may receive the first internal clock signals INCK1, the second internal clock signals INCK2 and the third internal clock signal pair INCK3/INCK3B. Based on the first internal clock signals INCK1, the second internal clock signals INCK2 and the third internal clock signal pair INCK3/INCK3B, the data path **460** may transfer, to the memory core **470**, the data DQ provided from the external apparatus **110** through the data bus **140** of FIG. **1**. Based on the first internal clock signals INCK1, the second internal clock signals INCK2 and the third internal clock signal pair INCK3/INCK3B, the data path **460** may transfer, to the external apparatus **110** through the data bus **140**, data DQ provided from the memory core **470**. In an embodiment, the data path **460** may serialize, by utilizing the first internal clock signals INCK1, the second internal clock signals INCK2, and the third internal clock signal pair INCK3/INCK3B, the data output from the memory core **470** and may provide the serialized data to the external apparatus **110**.

(83) FIG. **6** is a block diagram illustrating a configuration of a multi-phase clock generating circuit **500** in accordance with an embodiment. The multi-phase clock generating circuit **500** of FIG. **6** may be applied as the multi-phase clock generating circuit **450** illustrated in FIG. **5**. Hereinafter, described with reference to FIGS. **5** and **6** will be the configuration and the operation of the multi-phase clock generating circuit **500** in accordance with an embodiment. The multi-phase clock generating circuit **500** may receive the first reference clock signal pair RCK/RCKB from the first selecting circuit **440**. The multi-phase clock generating circuit **500** may receive the third internal clock signal pair INCK3/INCK3B from the second selecting circuit **480**. Based on the first reference clock signal pair RCK/RCKB and the third internal clock signal pair INCK3/INCK3B, the multi-phase clock generating circuit **500** may generate the second reference clock signal pair RCK2/RCK2B, the first internal clock signals INCK1, and the second internal clock signals INCK2. The multi-phase clock generating circuit **500** may output, as the second reference clock signal pair RCK2/RCK2B, at least one of the first reference clock signal pair RCK/RCKB and the third internal clock signal pair INCK3/INCK3B. The multi-phase clock generating circuit **500** may generate the first internal clock signals INCK1 by dividing at least one of the first reference clock signal pair RCK/RCKB and the third internal clock signal pair INCK3/INCK3B. The first internal clock signals INCK1 may include a plurality of internal clock signals. Further, the multi-phase clock generating circuit **500** may generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The second internal clock signals INCK2 may include a plurality of internal clock signals. The first internal clock signals INCK1 may include an internal clock signal ICK, an internal clock signal QCK, an internal clock signal ICKB, and an internal clock signal QCKB. The second internal clock signals INCK2 may include an internal clock signal OCK0, an internal clock signal OCK2, an internal clock signal OCK4, and an internal clock signal OCK6. In an embodiment, the multi-phase clock generating circuit **500** may divide the first internal

clock signals INCK1 based on the third internal clock signal pair INCK3/INCK3B, which are the output signals from the second selecting circuit **480** illustrated in FIG. 5.

(84) The multi-phase clock generating circuit **500** may include an internal buffer **501**, a first divider **502**, and a second divider **503**. The internal buffer **501** may buffer the first reference clock signal pair RCK/RCKB to output the buffered signals as the second reference clock signal pair RCK2/RCK2B. For example, the internal buffer **501** may differentially amplify the first reference clock signal pair RCK/RCKB. The internal buffer **501** may be a differential amplifier configured to differentially amplify the first reference clock signal pair RCK/RCKB. The second reference clock signal pair RCK2/RCK2B may have substantially the same phase difference and substantially the same frequency as the first reference clock signal pair RCK/RCKB. The first divider **502** may divide the first reference clock signal pair RCK/RCKB to generate the first internal clock signals INCK1. The first internal clock signals INCK1 may include the plurality of first internal clock signals. For example, the first divider **502** may divide frequency of the first reference clock signal pair RCK/RCKB by 2 to generate the first internal clock signals INCK1. The first internal clock signals INCK1 may include the internal clock signal ICK, the internal clock signal QCK, the internal clock signal ICKB, and the internal clock signal QCKB. Each of the plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may have a frequency twice lower than the first reference clock signal pair RCK/RCKB. The plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may sequentially have a phase difference of 90° between each other. The plurality of first internal clock signals ICK, QCK, ICKB, and QCKB may the same frequency. The first divider **502** may receive the third internal clock signal pair INCK3/INCK3B. Based on the third internal clock signal pair INCK3/INCK3B, the first divider **502** may divide the first reference clock signal pair RCK/RCKB. For example, the first divider **502** may divide the first reference clock signal pair RCK/RCKB in synchronization with a rising edge or a falling edge of the third internal clock signal pair INCK3/INCK3B. The first divider **502** may divide the first reference clock signal pair RCK/RCKB in synchronization with the third internal clock signal pair INCK3/INCK3B, which increases the signal characteristics of the first internal clock signals INCK1.

(85) The second divider **503** may further generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1. The second internal clock signals INCK2 may include the plurality of second internal clock signals. For example, the second divider **503** may divide frequency of the first internal clock signals INCK1 by two to generate the second internal clock signals INCK2. The second internal clock signals INCK2 may include the internal clock signal OCK0, the internal clock signal OCK2, the internal clock signal OCK4, and the internal clock signal OCK6. Each of the plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6 may have a frequency four (4) times lower than the first reference clock signal pair RCK/RCKB. The plurality of second internal clock signals OCK0, OCK2, OCK4, and OCK6 may sequentially have a phase difference of 90° between each other.

(86) In an embodiment, the multi-phase clock generating circuit **500** illustrated in FIG. 6 may be applied as any of the multi-phase clock generating circuit **124** illustrated in FIG. 1, the multi-phase clock generating circuit **250** illustrated in FIG. 2, and the multi-phase clock generating circuit **350** illustrated in FIG. 4.

(87) When the multi-phase clock generating circuit **500** illustrated in FIG. 6 is applied as the multi-phase clock generating circuit **124** illustrated in FIG. 1, the internal buffer **501** illustrated in FIG. 6 may be modified to output, as the third internal clock signal pair INCK3/INCK3B, one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B instead of the first reference clock signal pair RCK/RCKB. Further, the first divider **502** illustrated in FIG. 6 may be modified to divide one of the first clock signal pair CK1/CK1B, the second clock signal pair CK2/CK2B, and the third clock signal pair CK3/CK3B to generate the first internal clock signals INCK1. In an embodiment, the first divider **502** may be

modified not to receive the third internal clock signal pair INCK3/INCK3B. The second divider **503** may further generate the second internal clock signals INCK2 by dividing the first internal clock signals INCK1.

(88) When the multi-phase clock generating circuit **500** illustrated in FIG. **6** is applied as the multi-phase clock generating circuit **250** illustrated in FIG. **2**, the internal buffer **501** illustrated in FIG. **6** may be modified to output the first reference clock signal pair RCK/RCKB as the third internal clock signal pair INCK3/INCK3B. In an embodiment, the first divider **502** might not receive the third internal clock signal pair INCK3/INCK3B.

(89) When the multi-phase clock generating circuit **500** illustrated in FIG. **6** is applied as the multi-phase clock generating circuit **350** illustrated in FIG. **4**, the first divider **502** illustrated in FIG. **6** may be modified not to receive the third internal clock signal pair INCK3/INCK3B from the second selecting circuit **380** illustrated in FIG. **4**.

(90) While certain embodiments have been described above, it will be understood by those skilled in the art that the embodiments described are by way of example only. Accordingly, the semiconductor apparatus including the plurality of clock paths and the semiconductor system using the same should not be limited based on the described embodiments. Rather, the semiconductor apparatus including the plurality of clock paths and the semiconductor system using the same described herein should only be limited by the claims that follow when taken in conjunction with the above description and accompanying drawings.

Claims

1. A semiconductor apparatus including a plurality of clock paths, the semiconductor apparatus comprising: a first clock path configured to buffer a system clock signal pair to generate a first clock signal pair in a first operation mode; a second clock path configured to multiply a frequency of the system clock signal pair to generate a second clock signal pair in a second operation mode; a third clock path configured to convert the system clock signal pair to a Complementary Metal-Oxide-Semiconductor (CMOS) level to generate a third clock signal pair in a third operation mode; a first selecting circuit configured to output, as a first reference clock signal pair, one of the first clock signal pair, the second clock signal pair, and the third clock signal pair according to the operation mode; and a multi-phase clock generating circuit configured to generate first internal clock signals from the first reference clock signal pair.
2. The semiconductor apparatus of claim 1, wherein the system clock signal pair in the first operation mode has a frequency within a first frequency range, wherein the system clock signal pair in the second operation mode has a frequency within a second frequency range higher than the first frequency range, and wherein the system clock signal pair in the third operation mode has a frequency within a third frequency range higher than the second frequency range.
3. The semiconductor apparatus of claim 1, wherein the system clock signal pair in the second operation mode has a phase difference of 90° .
4. The semiconductor apparatus of claim 1, wherein the system clock signal pair in any of the first operation mode and the third operation mode has a phase difference of 180° .
5. The semiconductor apparatus of claim 1, wherein each of the first clock signal pair, the second clock signal pair, and the third clock signal pair has a phase difference of 180° .
6. The semiconductor apparatus of claim 1, wherein the multi-phase clock generating circuit is configured to output the first reference clock signal pair as the first internal clock signals or configured to divide the first reference clock signal pair to generate the first internal clock signals.
7. The semiconductor apparatus of claim 1, wherein the first clock path includes: a first receiving circuit configured to receive the system clock signal pair; and a buffer circuit configured to buffer output signals from the first receiving circuit to generate the first clock signal pair.
8. The semiconductor apparatus of claim 1, wherein the second clock path includes: a second

receiving circuit configured to receive the system clock signal pair; and a multiplier configured to multiply a frequency of output signals from the second receiving circuit to generate the second clock signal pair.

9. The semiconductor apparatus of claim 1, wherein the third clock path includes: a third receiving circuit configured to receive the system clock signal pair; and a converter configured to convert output signals from the third receiving circuit to the CMOS level to generate the third clock signal pair.

10. A semiconductor apparatus including a plurality of clock paths, the semiconductor apparatus comprising: a first clock path configured to buffer a system clock signal pair to generate a first clock signal pair in a first operation mode; a second clock path configured to multiply a frequency of the system clock signal pair to generate a second clock signal pair in a second operation mode; a third clock path configured to convert the system clock signal pair to a Complementary Metal-Oxide-Semiconductor (CMOS) level to generate a third clock signal pair and configured to buffer the system clock signal pair to a Current Mode Logic (CML) level to generate a fourth clock signal pair, in a third operation mode; a first selecting circuit configured to select, as a first reference clock signal pair, one of the first clock signal pair, the second clock signal pair, and the third clock signal pair according to the operation mode; a multi-phase clock generating circuit configured to generate first internal clock signals, second internal clock signals, and a second reference clock signal pair from the first reference clock signal pair; and a second selecting circuit configured to select, according to the operation mode, at least one of the second reference clock signal pair and the fourth clock signal pair to output the selected pair as a third internal clock signal pair.

11. The semiconductor apparatus of claim 10, wherein the system clock signal pair in the first operation mode has a frequency within a first frequency range, wherein the system clock signal pair in the second operation mode has a frequency within a second frequency range higher than the first frequency range, and wherein the system clock signal pair in the third operation mode has a frequency within a third frequency range higher than the second frequency range.

12. The semiconductor apparatus of claim 10, wherein the system clock signal pair in the second operation mode has a phase difference of 90° , and wherein the system clock signal pair in any of the first operation mode and the third operation mode has a phase difference of 180° .

13. The semiconductor apparatus of claim 10, wherein the multi-phase clock generating circuit is configured to output the first reference clock signal pair as the second reference clock signal pair or configured to divide the first reference clock signal pair to generate the first internal clock signals and the second internal clock signals.

14. The semiconductor apparatus of claim 10, wherein the first clock path includes: a first receiving circuit configured to receive the system clock signal pair; and a buffer circuit configured to buffer output signals from the first receiving circuit to generate the first clock signal pair.

15. The semiconductor apparatus of claim 10, wherein the second clock path includes: a second receiving circuit configured to receive the system clock signal pair; and a multiplier configured to multiply a frequency of output signals from the second receiving circuit to generate the second clock signal pair.

16. The semiconductor apparatus of claim 10, wherein the third clock path includes: a third receiving circuit configured to receive the system clock signal pair; a first converter configured to convert output signals from the third receiving circuit to the CMOS level to generate the third clock signal pair; a CML buffer configured to buffer the output signals from the third receiving circuit to the CML level; and a second converter configured to convert output signals from the CML buffer to the CMOS level to generate the fourth clock signal pair.

17. A semiconductor apparatus including a plurality of clock paths, the semiconductor apparatus comprising: a first clock path configured to buffer a system clock signal pair to generate a first clock signal pair in a first operation mode; a second clock path configured to multiply a frequency of the system clock signal pair to generate a second clock signal pair in a second operation mode; a

third clock path configured to convert the system clock signal pair to a Complementary Metal-Oxide-Semiconductor (CMOS) level to generate a third clock signal pair and configured to buffer the system clock signal pair to a Current Mode Logic (CML) level to generate a fourth clock signal pair, in a third operation mode; a first selecting circuit configured to selecting, as a first reference clock signal pair, one of the first clock signal pair, the second clock signal pair, and the third clock signal pair according to the operation mode; a multi-phase clock generating circuit configured to generate first internal clock signals, second internal clock signals, and a second reference clock signal pair based on at least one of a third internal clock signal pair and the first reference clock signal pair; and a second selecting circuit configured to select one of the second reference clock signal pair and the fourth clock signal pair to output the selected pair as the third internal clock signal pair.

18. The semiconductor apparatus of claim 17, wherein the system clock signal pair in the first operation mode has a frequency within a first frequency range, wherein the system clock signal pair in the second operation mode has a frequency within a second frequency range higher than the first frequency range, and wherein the system clock signal pair in the third operation mode has a frequency within a third frequency range higher than the second frequency range.

19. The semiconductor apparatus of claim 17, wherein the system clock signal pair in the second operation mode has a phase difference of 90° , and wherein the system clock signal pair in any of the first operation mode and the third operation mode has a phase difference of 180° .

20. The semiconductor apparatus of claim 17, wherein the multi-phase clock generating circuit is configured to output, as the second reference clock signal pair, one of the first reference clock signal pair and the third internal clock signal pair or configured to divide one of the first reference clock signal pair and the third internal clock signal pair to generate the first internal clock signals and the second internal clock signals.

21. The semiconductor apparatus of claim 17, wherein the first clock path includes: a first receiving circuit configured to receive the system clock signal pair; and a buffer circuit configured to buffer output signals from the first receiving circuit to generate the first clock signal pair.

22. The semiconductor apparatus of claim 17, wherein the second clock path includes: a second receiving circuit configured to receive the system clock signal pair; and a multiplier configured to multiply a frequency of output signals from the second receiving circuit to generate the second clock signal pair.

23. The semiconductor apparatus of claim 17, wherein the third clock path includes: a third receiving circuit configured to receive the system clock signal pair; a first converter configured to convert output signals from the third receiving circuit to the CMOS level to generate the third clock signal pair; a CML buffer configured to buffer the output signals from the third receiving circuit to the CML level; and a second converter configured to convert output signals from the CML buffer to the CMOS level to generate the fourth clock signal pair.
